











- ► PCB / CHIP LED
- ▶ 0603 (1608) 0.4t
- ► Green (525nm)

NOR49S82



0603 0.4t Series





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APPLICATIONS:

- Backlighting
- Indication Light
- Switch light
- Dashboard

FEATURES:

- Package: PCB / CHIP LED Mono Colour Package
- Forward Current: 20mAForward Voltage (typ.): 3.2V
- Luminous Intensity (typ.): 470mcd @20mA
- Colour: GreenWavelength: 525nmViewing angle: 150°
- Materials:Die: InGaN
- Resin: Epoxy (Water Clear)
 Operating Temperature: -40~+80°C
- Storage Temperature: -40~+85°C
- Grouping parameters:
 - Forward voltage
 - Luminous intensity
 - Dominant wavelength
- Soldering methods: Reflow
- Preconditioning: acc. to JEDEC Level 3
- Packing: 8mm tape with Max.4000/reel, ø180mm (7")



CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current	IF	30	mA
Peak Forward Current Duty 1/8@1KHz	I _{FP}	125	mA
Reverse Voltage	VR	5	V
Reverse Current @5V	I _R	10	μΑ
Power Dissipation	P _D	111	mW
Operating Temperature	T _{OPR}	-40~+80	°C
Storage Temperature	T _{STG}	-40~+85	°C

Electrical & Optical Characteristics (Ta=25°C)

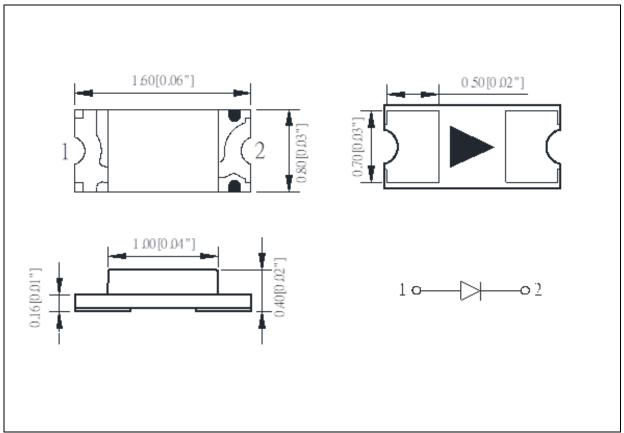
Parameter Symbol		Values			Unit	Test
Parameter Sym	Зуппоп	Min.	Тур.	Max.	Unit	Condition
Forward Voltage	V _F	2.8	3.2	3.7	V	I _F =20mA
Luminous Intensity	I _V	250	470	800	mcd	I _F =20mA
Dominant Wavelength	λ_{D}	520	525	530	nm	I _F =20mA
Peak Wavelength	$\lambda_{ extsf{P}}$		520		nm	I _F =20mA
Spectral Line Half Bandwidth	Δλ		33		nm	I _F =20mA
Viewing Angle	2θ _{1/2}		150		deg	I _F =20mA

^{1.} Luminous intensity (I_V) ±15%, Forward Voltage (V_F) ±0.1V, Viewing angle(2 $\theta_{1/2}$) ±5%



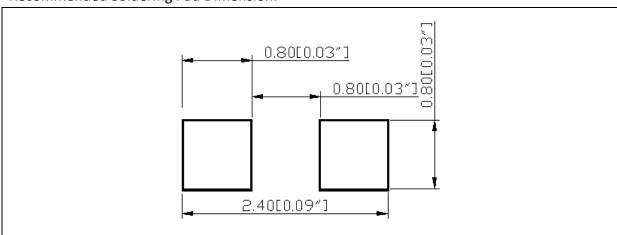
OUTLINE DIMENSION:

Package Dimension:



- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.2mm, unless otherwise noted.

Recommended Soldering Pad Dimension:



- 1. Dimensions are in millimetre (mm).
- 2. Tolerance ±0.1mm with angle tolerance ±0.5°.



BINNING GROUPS:

Forward Voltage Classifications (I_F = 20mA):

Code	Min.	Max.	Unit
F	2.8	3.1	
G	3.1	3.4	V
Н	3.4	3.7	

Luminous Intensity Classifications (I_F = 20mA):

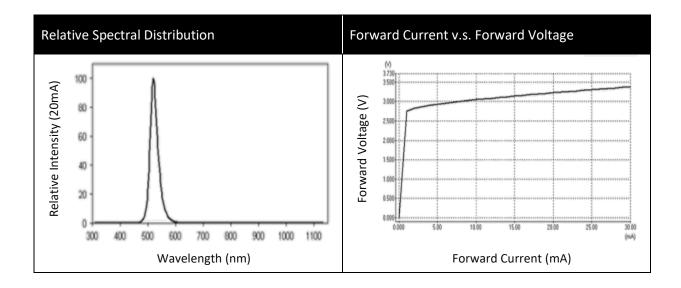
Code	Min.	Max.	Unit
N	250	320	
0	320	400	
Р	400	500	mcd
Q	500	630	
R	630	800	

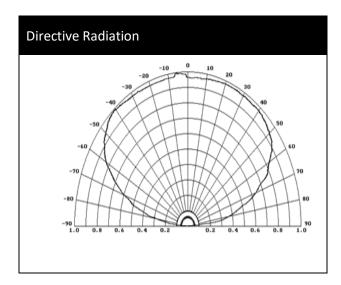
Dominant Wavelength Classifications (I_F = 20mA):

Code	Min.	Max.	Unit
U	520	522.5	
V	522.5	525	
W	525	527.5	nm
X	527.5	530	



ELECTRO-OPTICAL CHARACTERISTICS:

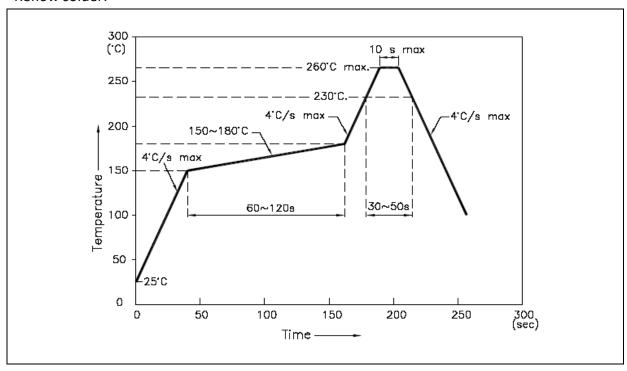






RECOMMENDED SOLDERING PROFILE:

Reflow solder:



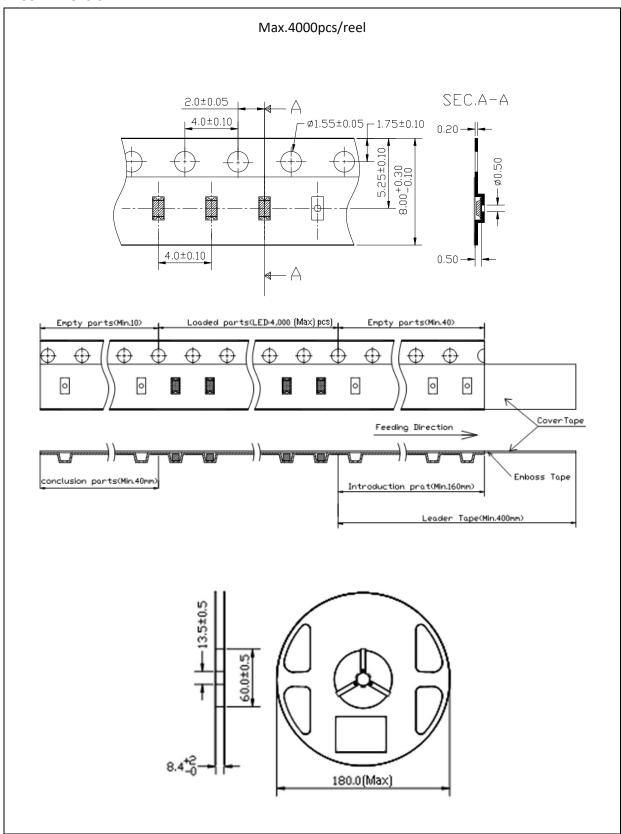
Note:

- 1. Recommend reflow temperature 245°C. The maximum soldering temperature should be limited to 260°C.
- 2. Maximum reflow soldering: 2 times.
- 3. Before, during, and after soldering, should not apply stress on the components and PCB board.



PACKING SPECIFICATION:

Reel Dimension:





PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent and apply baking.

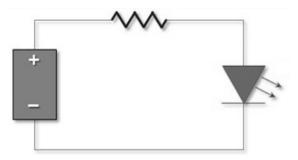
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

• 60±3°C x 24hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.



REVISION RECORD:

Version	Date	Summary of Revision
A1.0	09/08/2019	Datasheet set-up.